

[TITLE OF DOCUMENT] ABSTRACT

A soldering alloy comprising an alloy composition consisting of 13-22 mass% of In, 0.5-2.8 mass% of Ag, 0.5-5.0 mass% of Bi, 0.002-0.05 mass% of Ni, and a balance Sn. A soldering alloy, a soldering paste, a preform solder, a soldering ball, a wire solder, a resin
5 flux cored solder and a solder joint, each of which is composed of the soldering alloy. An electronic circuit board and a multi-layer electronic circuit board joined by using the solder joint.